

LTM8032 71-BGA 15mm X 9mm X 3.42mm - Solder (DA) (TABLE OF MATERIAL DECLARATION)

The LTM8032 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1480	Barium Compounds	7727-43-7	0.00379	2.56
				Bismaleimide/Triazine/Resin/Filler Substances (Silica Crystalline)	105391-33-1, 1156-51-0/9003-36-5/21645-51-2, non-disclosure	0.02830	19.12
				Copper Metal	7440-50-8	0.08375	56.59
				Copper Compounds	147-14-8	0.00033	0.22
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00001	0.01
				Gold metal or alloy	7440-57-5	0.00022	0.15
				Nickel	7440-02-0	0.00107	0.72
				Zinc	7440-66-6	0.00016	0.11
				Continuous Filament Fiber Glass	65997-17-3	0.02224	15.03
				Acrylic Resin	non-disclosure	0.00722	4.88
				Epoxy Resin	non-disclosure	0.00002	0.02
				Chromium(III) Oxide	1308-38-9	0.00001	0.00
				Silica Amorphous	7631-86-9	0.00007	0.05
				Talc;not containing fiber like asbestos	14807-96-6	0.00044	0.30
				Aromatic carbonyl compounds	non-disclosure	0.00041	0.28
				Cyanoguanidine	461-58-5	0.00001	0.01
				Calcium caarbonate	471-34-1	0.00044	0.00
				Amine compounds	non-disclosure	0.00005	0.04
				Leveling agent and others	non-disclosure	0.00016	0.11
				2	Solder Paste	Alloy	0.0009
Sb	7440-36-0	0.00004	5.00				
3	Passive/Active Components		0.5558	Iron Powder (Fe)	7439-89-6	0.29834	53.73
				Copper (Cu)	7440-50-8	0.19325	34.77
				Nickel (Ni)	7440-02-0	0.00855	1.54
				Tin (Sn)	7440-31-5	0.00285	0.51
				Ceramic (Ba Compounds)	12047-27-7	0.05220	9.45
4	Active Ics	Silicon	0.0025	Silicon	7440-21-3	0.00250	100.00
5	solder ball		0.0840	Sn	7440-31-5	0.08106	96.50
				Ag	7440-22-4	0.00252	3.00
				Cu	7440-50-8	0.00042	0.50
6	Wire	Gold	0.0037	Au	7440-57-5	0.00370	99.99
7	Encapsulation	Epoxy Resin	0.4823	Fused Silica	60676-86-0	0.37232	77.20
				Epoxy Resin	non-disclosure	0.04292	8.90
				Phenol Resin	non-disclosure	0.04292	8.90
				Crytalline Silica	14808-60-7	0.01447	3.00
				Carbon Black	1333-86-4	0.00241	0.50
				Metal Hydroxide	non-disclosure	0.00723	1.50
Total Package Weight			1.2771				

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts